

Current Production Information							
TI Part Number		ADS8327IPW		Assembly Site		TI MALAYSIA A/T	
Lead/Ball Finish		CU NIPDAU		Package Type / Pins		PW 16	
Planned Lead/Ball Finish				Package Body Size (WxLxH) mm		4.4x5x1.15	
MSL / Reflow Ratings		Level-2-260C-1 YEAR		Total Device Mass (mg)		61.94303600000001	
Environmental Ratings Information							
Part Number Type		Std		JIG Material Content Compliance		Level A & B	
RoHS & High-Temp Compliant		Y		Green Compliant		Y	
Pb-Free (RoHS) Conversion Date		01-Jul-2005 (DC 0527)		Green Conversion Date		01-Jul-2005 (DC 0527)	
Pb-Free (RoHS) Available Supply Date		07-Jun-2006		Green Available Supply Date		07-Jun-2006	
Component Information							
Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Metallurgy	Gold	7440-57-5	0.2277	98.9978	989978	0.3676	3675
Trace Metal	Beryllium	7440-41-7	0	0	0	0	0
Trace Metal	Calcium	7440-70-2	0.000005	0.0022	21	0	0
Trace Metal	Copper	7440-50-8	0.000345	0.15	1499	0.0006	5
Trace Metal	Palladium	7440-05-3	0.001955	0.85	8499	0.0032	31
Trace Metal	Silver	7440-22-4	0	0	0	0	0
Sub-Total			0.230005	100	1000000	0.3713	3711
Die Attach Adhesive							
Conductive Material	Silver	7440-22-4	0.042	70	700000	0.0678	678
Polymer	Epoxy		0.0078	13	130000	0.0126	125
Polymer	Proprietary Resin		0.0033	5.5	55000	0.0053	53
Reactive Diluent	Proprietary Material		0.0069	11.5	115000	0.0111	111
Sub-Total			0.06	100	1000000	0.0969	967
Lead Frame							
Base Metal	Chromium	7440-47-3	0.050898	0.25	2500	0.0822	821
Base Metal	Copper	7440-50-8	20.216488	99.3	992999	32.6372	326372
Base Metal	Tin	7440-31-5	0.050898	0.25	2500	0.0822	821
Base Metal	Zinc	7440-66-6	0.040718	0.2	1999	0.0657	657
Sub-Total			20.359002	100	1000000	32.8673	328671
Lead Frame Plating							
Plating	Gold	7440-57-5	0.00032	0.7805	7804	0.0005	5
Plating	Nickel	7440-02-0	0.038999	95.1195	951195	0.063	629
Plating	Palladium	7440-05-3	0.001681	4.1	41000	0.0027	27
Sub-Total			0.041	100	1000000	0.0662	661
Mold Compound							
Coloring	Carbon Black	1333-86-4	0.120909	0.3	2999	0.1952	1951
Filler	Fused Silica	60676-86-0	35.063635	87	869999	56.6063	566062
Flame Retardant Additive	Metal Hydroxide		0.40303	1	9999	0.6506	6506
Hardener	Proprietary Hardener		2.015151	5	49999	3.2532	32532
Other additives	Catalyst Mold Release Adhesion Agent		0.685152	1.7	17000	1.1061	11061
Polymer	Biphenyl Epoxy		0.806061	2	20000	1.3013	13012
Polymer	Proprietary Epoxy		1.209091	3	30000	1.9519	19519
Sub-Total			40.303029	100	1000000	65.0647	650643
Semiconductor Device							
Silicon Chip	Doped Silicon	7440-21-3	0.95	100	1000000	1.5337	15336
Sub-Total			0.95	100	1000000	1.5337	15336
Total			61.943036			100	1000000

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights. See Product Content Methodology.](#)

Material Declaration Certificate for Semiconductor Products

TI certifies that the material content information provided by TI as of the date of disclosure is representative and accurate. TI semiconductor products designated by TI as "Pb-Free" or "Green" (defined below) do not exceed any of the Joint Industry Guide (JIG) Level-A Substance thresholds and are compliant with the requirements of the European Union's Restriction on Use of Hazardous Substances ("RoHS") Directive, 2002/95/EC.

For TI semiconductor products NOT designated as "Pb-Free" or "Green", these products are RoHS compliant with the exception of Lead (Pb) which may be found in the leadframe plating or solder balls, or in RoHS exempt applications such as high-temperature solder die attach (exemption 7a) and flip-chip solder bumps (exemption 15). This situation is known as RoHS-5 or "5 of 6" compliant.

JIG Level-A Banned Substances	Threshold, Homogeneous Level (1)
Asbestos	Not intentionally added
Azo colorants	Not intentionally added
RoHS - Cadmium/Cadmium Compounds	75 ppm, Not intentionally added (RoHS threshold = 100ppm)
RoHS - Hexavalent Chromium/Hex.Chromium.Compounds	1000 ppm, Not intentionally added
RoHS - Lead/Lead Compounds	1000 ppm, Not intentionally added
RoHS - Mercury/Mercury Compounds	1000 ppm, Not intentionally added
Ozone Depleting Substances	Class I : Not intentionally added Class II : 1000ppm
RoHS - Polybrominated Biphenyls (PBBs)	1000 ppm, Not intentionally added
RoHS - Polybrominated Diphenyl Ethers (PBDEs)	1000 ppm, Not intentionally added
Polychlorinated Biphenyls (PCBs)	1000 ppm, Not intentionally added
Polychlorinated Naphthalenes (>3 Chlorine atoms)	1000 ppm, Not intentionally added
Radioactive Substances	1000 ppm, Not intentionally added
Shortchain Chlorinated Paraffins	1000 ppm, Not intentionally added
Tributyl Tin (TBT) and Triphenyl Tin (TPT)	1000 ppm, Not intentionally added
Tributyl Tin Oxide (TBTO)	1000 ppm, Not intentionally added

(1) Threshold does not apply to applications covered by a RoHS substance exemption.

Regarding the EU Directive 2004/12/EC concerning Packaging and Packaging Waste, TI's packing materials (boxes, trays, etc) comply with the directive's requirement that the total concentration of the 4 heavy metals (cadmium, hexavalent chromium, lead, and mercury) must not exceed 100 ppm. Material content details for TI's packing materials are available at www.ti.com/eoinfo.

TI bases its material content knowledge on information provided by third parties and has taken and continues to take commercially reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain limited information to be proprietary, and thus CAS numbers and other limited information may not be available for release. TI's standard warranty and limitation of liability provisions of TI's Standard Terms and Conditions (available at <http://www.ti.com/sc/docs/stdterms.htm>) apply to the representations herein unless otherwise provided by a written contract or other agreement signed by the parties.

Signature: [\(click here for signed certificate\)](#)

Name/Title: Cindy Allen, Vice President, Worldwide Quality

Date: September 27, 2006

Pb-Free: TI defines "Pb-Free" or "RoHS Compliant" to mean semiconductor products that are compliant with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials unless exempt. Where designed to be soldered at high temperatures, TI "Pb-Free" and "RoHS Compliant" products are suitable for use in specified lead-free processes.

Green: TI defines "Green" to mean Pb-Free/RoHS Compliant and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material).